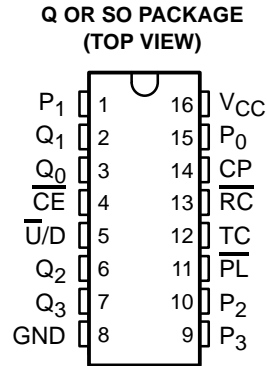


- Function, Pinout, and Drive Compatible With FCT and F Logic
- Reduced  $V_{OH}$  (Typically = 3.3 V) Versions of Equivalent FCT Functions
- Edge-Rate Control Circuitry for Significantly Improved Noise Characteristics
- $I_{off}$  Supports Partial-Power-Down Mode Operation
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)
- Matched Rise and Fall Times
- 64-mA Output Sink Current  
32-mA Output Source Current



### description

The CY74FCT191T is a reversible modulo-16 binary counter, featuring synchronous counting and asynchronous presetting. The preset allows the CY74FCT191T to be used in programmable dividers. The count enable input, terminal count output, and ripple-clock output make possible a variety of methods of implementing multiusage counters. In the counting modes, state changes are initiated by the rising edge of the clock.

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

**PIN DESCRIPTION**

NAME	DESCRIPTION
$\overline{CE}$	Count enable input (active low)
CP	Clock pulse input (active rising edge)
P	Parallel data inputs
$\overline{PL}$	Asynchronous parallel load input (active low)
$\overline{U/D}$	Up/down count control input
Q	Flip-flop outputs
$\overline{RC}$	Ripple clock output (active low)
TC	Terminal count output



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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# CY74FCT191T

## 4-BIT UP/DOWN BINARY COUNTER

SCCS016A – MAY 1994 – REVISED SEPTEMBER 2001



### ORDERING INFORMATION

T <sub>A</sub>	PACKAGE†		SPEED (ns)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	QSOP – Q	Tape and reel	6.2	CY74FCT191CTQCT	FT191-3
	SOIC – SO	Tube	6.2	CY74FCT191CTSOC	FCT191C
		Tape and reel	6.2	CY74FCT191CTSOCT	
	SOIC – SO	Tube	7.8	CY74FCT191ATSOC	FCT191A
		Tape and reel	7.8	CY74FCT191ATSOCT	


† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

### Function Tables

#### $\overline{RC}$ FUNCTION

INPUTS		OUTPUTS	
$\overline{CE}$	CP	TC†	$\overline{RC}$
L		H	
H	X	X	H
X	X	L	H

H = High logic level, L = Low logic level,

X = Don't care,  = Low pulse

† TC is generated internally.

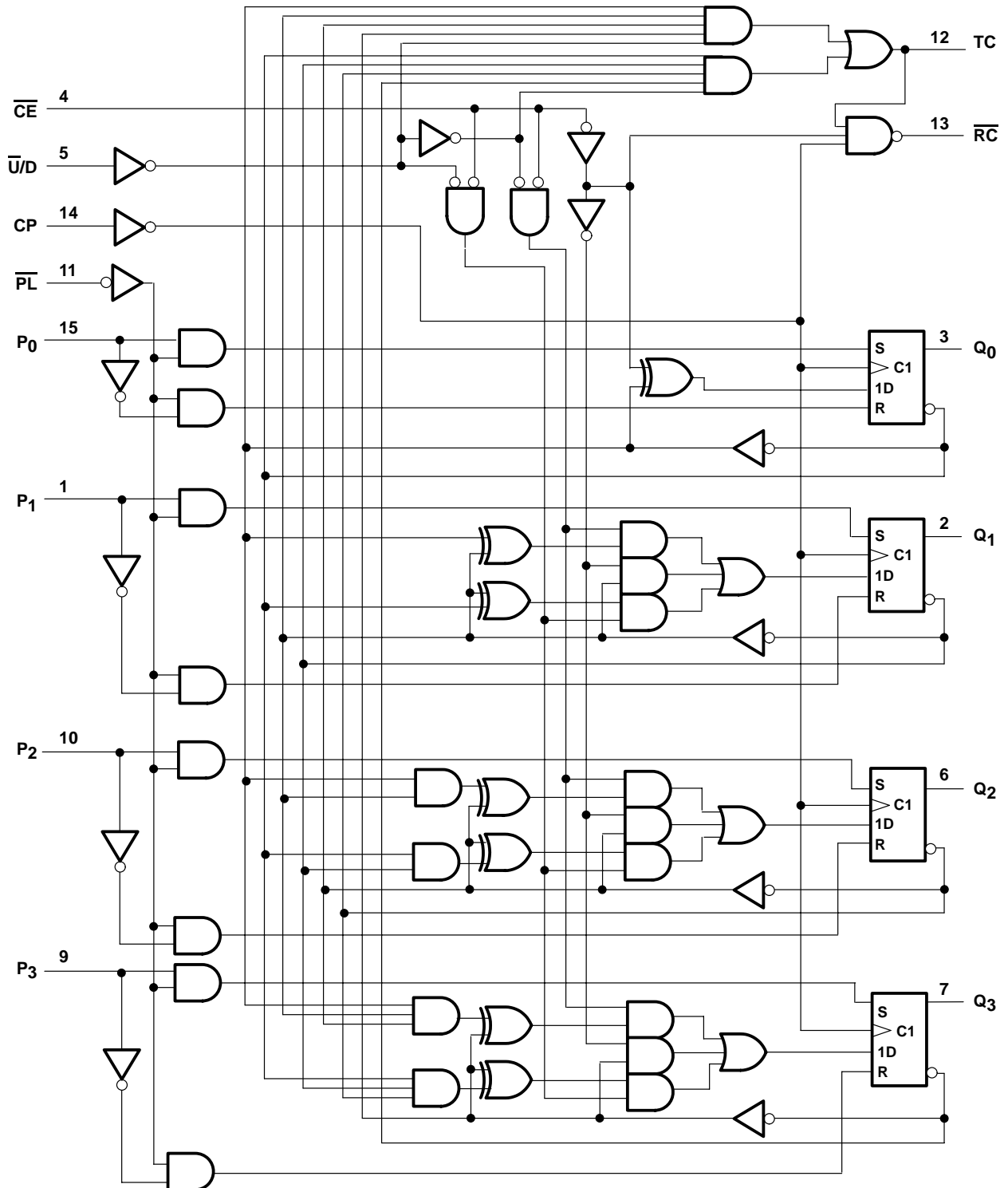
#### MODE SELECT

INPUTS				MODE
$\overline{PL}$	$\overline{CE}$	$\overline{U/D}$	CP	
H	L	L	↑	Count up
H	L	H	↑	Count down
L	X	X	X	Preset (asynchronous)
H	H	X	X	No change (hold)

H = High logic level, L = Low logic level, X = Don't care,

↑ = Low-to-high clock transition

**logic diagram (positive logic)**



CY74FCT191T  
4-BIT UP/DOWN BINARY COUNTER

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absolute maximum rating over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range to ground potential	–0.5 V to 7 V
DC input voltage range	–0.5 V to 7 V
DC output voltage range	–0.5 V to 7 V
DC output current (maximum sink current/pin)	120 mA
Package thermal impedance, $\theta_{JA}$ (see Note 1): Q package	90°C/W
SO package	57°C/W
Ambient temperature range with power applied, $T_A$	–65°C to 135°C
Storage temperature range, $T_{stg}$	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 2)

	MIN	NOM	MAX	UNIT
$V_{CC}$ Supply voltage	4.75	5	5.25	V
$V_{IH}$ High-level input voltage	2			V
$V_{IL}$ Low-level input voltage			0.8	V
$I_{OH}$ High-level output current			–32	mA
$I_{OL}$ Low-level output current			64	mA
$T_A$ Operating free-air temperature	–40		85	°C

NOTE 2: All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation.

**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS		MIN	TYP†	MAX	UNIT	
V <sub>IK</sub>	V <sub>CC</sub> = 4.75 V,	I <sub>IN</sub> = −18 mA		−0.7	−1.2	V	
V <sub>OH</sub>	V <sub>CC</sub> = 4.75 V,	I <sub>OH</sub> = −32 mA	2			V	
	V <sub>CC</sub> = 4.75 V,	I <sub>OH</sub> = −15 mA	2.4	3.3			
V <sub>OL</sub>	V <sub>CC</sub> = 4.75 V,	I <sub>OL</sub> = 64 mA		0.3	0.55	V	
V <sub>H</sub>	All inputs			0.2		V	
I <sub>I</sub>	V <sub>CC</sub> = 5.25 V,	V <sub>IN</sub> = V <sub>CC</sub>			5	μA	
I <sub>IH</sub>	V <sub>CC</sub> = 5.25 V,	V <sub>IN</sub> = 2.7 V			±1	μA	
I <sub>IL</sub>	V <sub>CC</sub> = 5.25 V,	V <sub>IN</sub> = 0.5 V			±1	μA	
I <sub>OS</sub> ‡	V <sub>CC</sub> = 5.25 V,	V <sub>OUT</sub> = 0 V	−60	−120	−225	mA	
I <sub>off</sub>	V <sub>CC</sub> = 0 V,	V <sub>OUT</sub> = 4.5 V			±1	μA	
I <sub>CC</sub>	V <sub>CC</sub> = 5.25 V, V <sub>IN</sub> ≤ 0.2 V, V <sub>IN</sub> ≥ V <sub>CC</sub> − 0.2 V			0.1	0.2	mA	
ΔI <sub>CC</sub>	V <sub>CC</sub> = 5.25 V, V <sub>IN</sub> = 3.4 V§, f <sub>1</sub> = 0, Outputs open			0.5	2	mA	
I <sub>CCD</sub> ¶	V <sub>CC</sub> = 5.25 V, One bit switching at 50% duty cycle, Preset mode, Outputs open, MR = V <sub>CC</sub> = SR, PL = CE = U/D = CP = GND, V <sub>IN</sub> ≤ 0.2 V or V <sub>IN</sub> ≥ V <sub>CC</sub> − 0.2 V			0.06	0.12	mA/MHz	
I <sub>C</sub> #	V <sub>CC</sub> = 5.25 V, Preset mode, Outputs open, PL = CE = U/D = CP = GND	One bit switching at f <sub>1</sub> = 5 MHz at 50% duty cycle	V <sub>IN</sub> = V <sub>CC</sub> or GND		0.4	0.8	mA
			V <sub>IN</sub> = 3.4 V or GND		0.7	1.8	mA
		Four bits switching at f <sub>1</sub> = 5 MHz at 50% duty cycle	V <sub>IN</sub> = V <sub>CC</sub> or GND		1.3	2.6	mA
			V <sub>IN</sub> = 3.4 V or GND		2.3	6.6	mA
C <sub>i</sub>				5	10	pF	
C <sub>o</sub>				9	12	pF	

† Typical values are at  $V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

‡ Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample-and-hold techniques are preferable to minimize internal chip heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output can raise the chip temperature well above normal and cause invalid readings in other parametric tests. In any sequence of parameter tests,  $I_{OS}$  tests should be performed last.

§ Per TTL-driven input ( $V_{IN} = 3.4\text{ V}$ ); all other inputs at  $V_{CC}$  or GND

¶ This parameter is derived for use in total power-supply calculations.

#  $I_C = I_{CC} + \Delta I_{CC} \times D_H \times N_T + I_{CCD} (f_0/2 + f_1 \times N_1)$

Where:

$I_C$  = Total supply current

$I_{CC}$  = Power-supply current with CMOS input levels

$\Delta I_{CC}$  = Power-supply current for a TTL high input ( $V_{IN} = 3.4\text{ V}$ )

$D_H$  = Duty cycle for TTL inputs high

$N_T$  = Number of TTL inputs at  $D_H$

$I_{CCD}$  = Dynamic current caused by an input transition pair (HLH or LHL)

$f_0$  = Clock frequency for registered devices, otherwise zero

$f_1$  = Input signal frequency

$N_1$  = Number of inputs changing at  $f_1$

All currents are in milliamperes and all frequencies are in megahertz.

|| Values for these conditions are examples of the  $I_{CC}$  formula.

# CY74FCT191T

## 4-BIT UP/DOWN BINARY COUNTER

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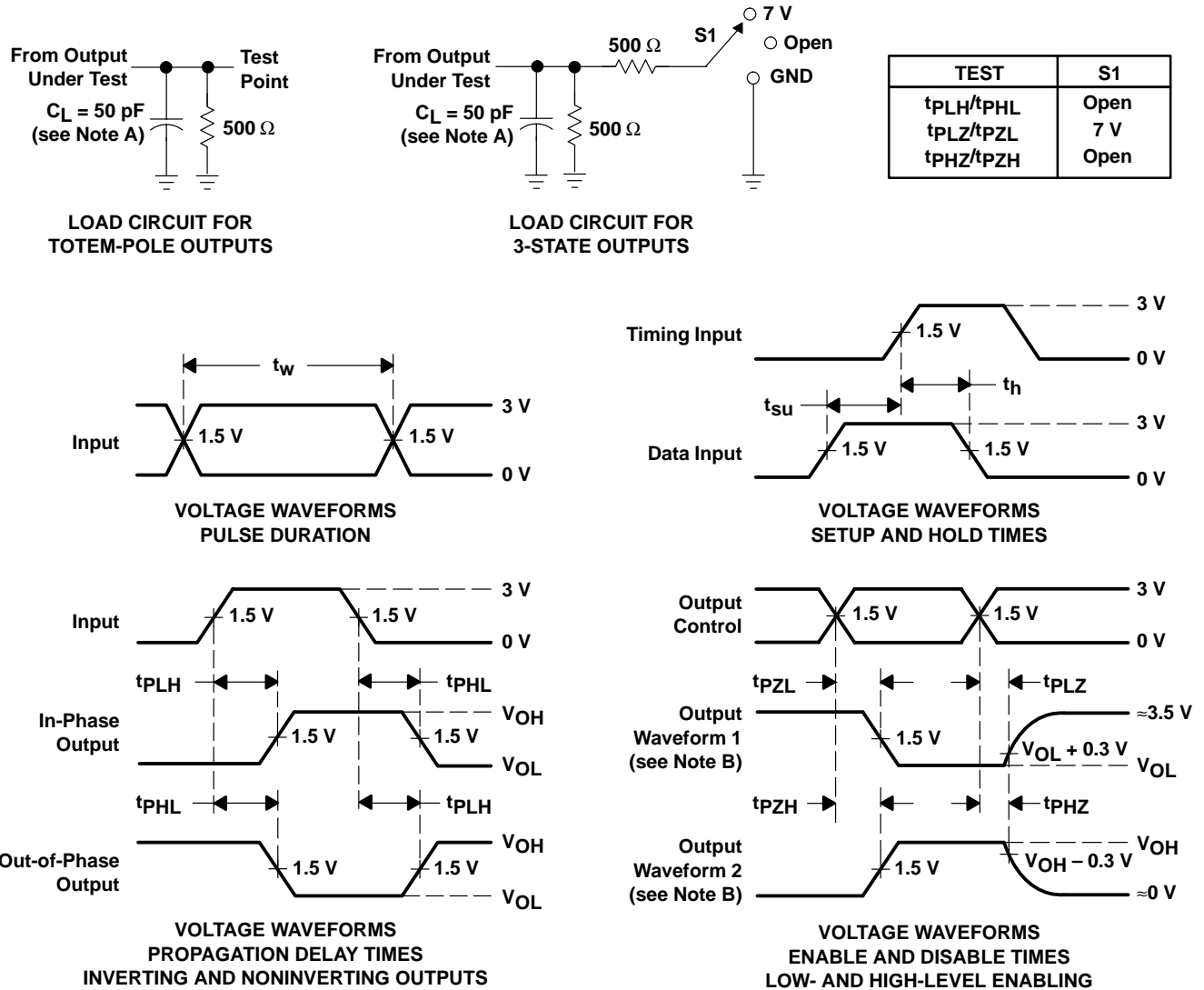
timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER			CY74FCT191AT		CY74FCT191CT		UNIT
			MIN	MAX	MIN	MAX	
$t_w$ Pulse duration	CP	High or Low	4		4		ns
	$\overline{PL}$ low		5.5		5		
$t_{su}$ Setup time	Data before $\overline{PL}\downarrow$	High or Low	4		3.5		ns
	$\overline{CE}$ before $CP\uparrow$	Low	9		7.2		
	$\overline{U/D}$ before $CP\uparrow$	High or Low	10		8		
$t_h$ Hold time	Data after $\overline{PL}\downarrow$	High or Low	1.5		1		ns
	$\overline{CE}$ after $CP\uparrow$	Low	0		0		
	$\overline{U/D}$ after $CP\uparrow$	High or Low	0		0		
$t_{rec}$ Recovery time	$\overline{PL}$ after $CP\uparrow$		5		4.5		ns

switching characteristics over operating free-air temperature range (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	CY74FCT191AT		CY74FCT191CT		UNIT
			MIN	MAX	MIN	MAX	
$t_{PLH}$	CP	$Q_n$	1.5	7.8	1.5	6.2	ns
$t_{PHL}$			1.5	7.8	1.5	6.2	
$t_{PLH}$	CP	TC	1.5	11.8	1.5	9.4	ns
$t_{PHL}$			1.5	11.8	1.5	9.4	
$t_{PLH}$	CP	$\overline{RC}$	1.5	8.5	1.5	6.8	ns
$t_{PHL}$			1.5	8.5	1.5	6.8	
$t_{PLH}$	CE	$\overline{RC}$	1.5	7.2	1.5	6	ns
$t_{PHL}$			1.5	7.2	1.5	6	
$t_{PLH}$	$\overline{U/D}$	$\overline{RC}$	1.5	13	1.5	11	ns
$t_{PHL}$			1.5	13	1.5	11	
$t_{PLH}$	$\overline{U/D}$	TC	1.5	7.2	1.5	6.1	ns
$t_{PHL}$			1.5	7.2	1.5	6.1	
$t_{PLH}$	$P_n$	$Q_n$	1.5	9.1	1.5	7.7	ns
$t_{PHL}$			1.5	9.1	1.5	7.7	
$t_{PLH}$	$\overline{PL}$	$Q_n$	2	8.5	2	7.2	ns
$t_{PHL}$			2	8.5	2	7.2	

## PARAMETER MEASUREMENT INFORMATION



- NOTES: A.  $C_L$  includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. The outputs are measured one at a time with one input transition per measurement.

**Figure 1. Load Circuit and Voltage Waveforms**

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
CY74FCT191ATSOC	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT191ATSOCE4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT191ATSOCG4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT191ATSOCT	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT191ATSOCTE4	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT191ATSOCTG4	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT191CTQCT	ACTIVE	SSOP/ QSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT191CTQCTE4	ACTIVE	SSOP/ QSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT191CTQCTG4	ACTIVE	SSOP/ QSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT191CTSOC	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT191CTSOCE4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT191CTSOCG4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT191CTSOCT	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT191CTSOCTG4	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

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**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

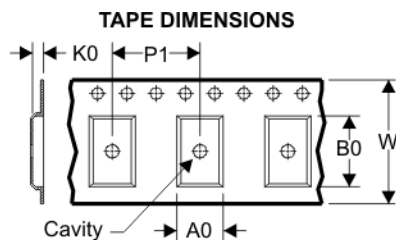
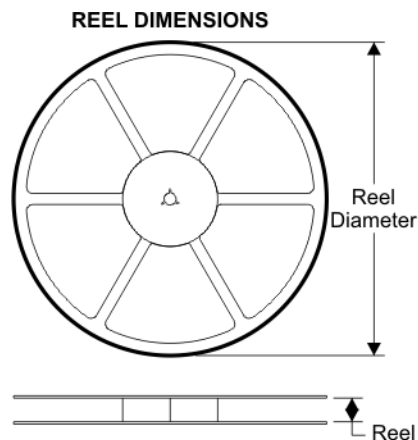
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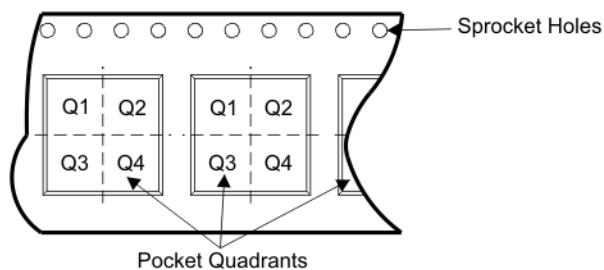
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**TAPE AND REEL BOX INFORMATION**



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**



Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CY74FCT191ATSOCT	DW	16	SITE 60	330	16	10.75	10.7	2.7	12	16	Q1
CY74FCT191CTQCT	DBQ	16	SITE 27	330	0	6.4	5.2	2.1	8	12	Q1
CY74FCT191CTSOCT	DW	16	SITE 60	330	16	10.75	10.7	2.7	12	16	Q1

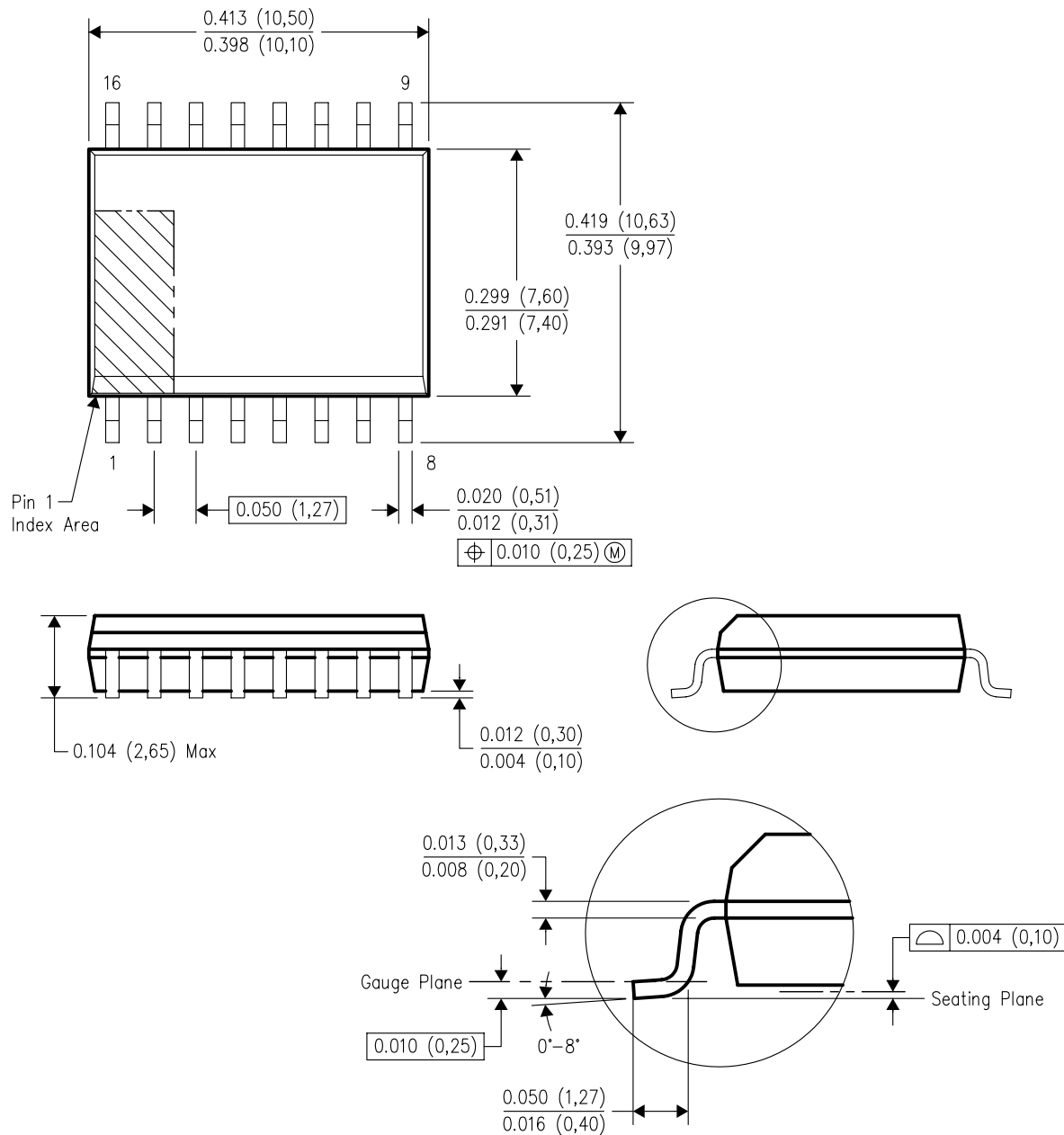
## TAPE AND REEL BOX DIMENSIONS



Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
CY74FCT191ATSOCT	DW	16	SITE 60	346.0	346.0	33.0
CY74FCT191CTQCT	DBQ	16	SITE 27	342.9	336.6	20.64
CY74FCT191CTSOCT	DW	16	SITE 60	346.0	346.0	33.0

DW (R-PDSO-G16)

# PLASTIC SMALL-OUTLINE PACKAGE

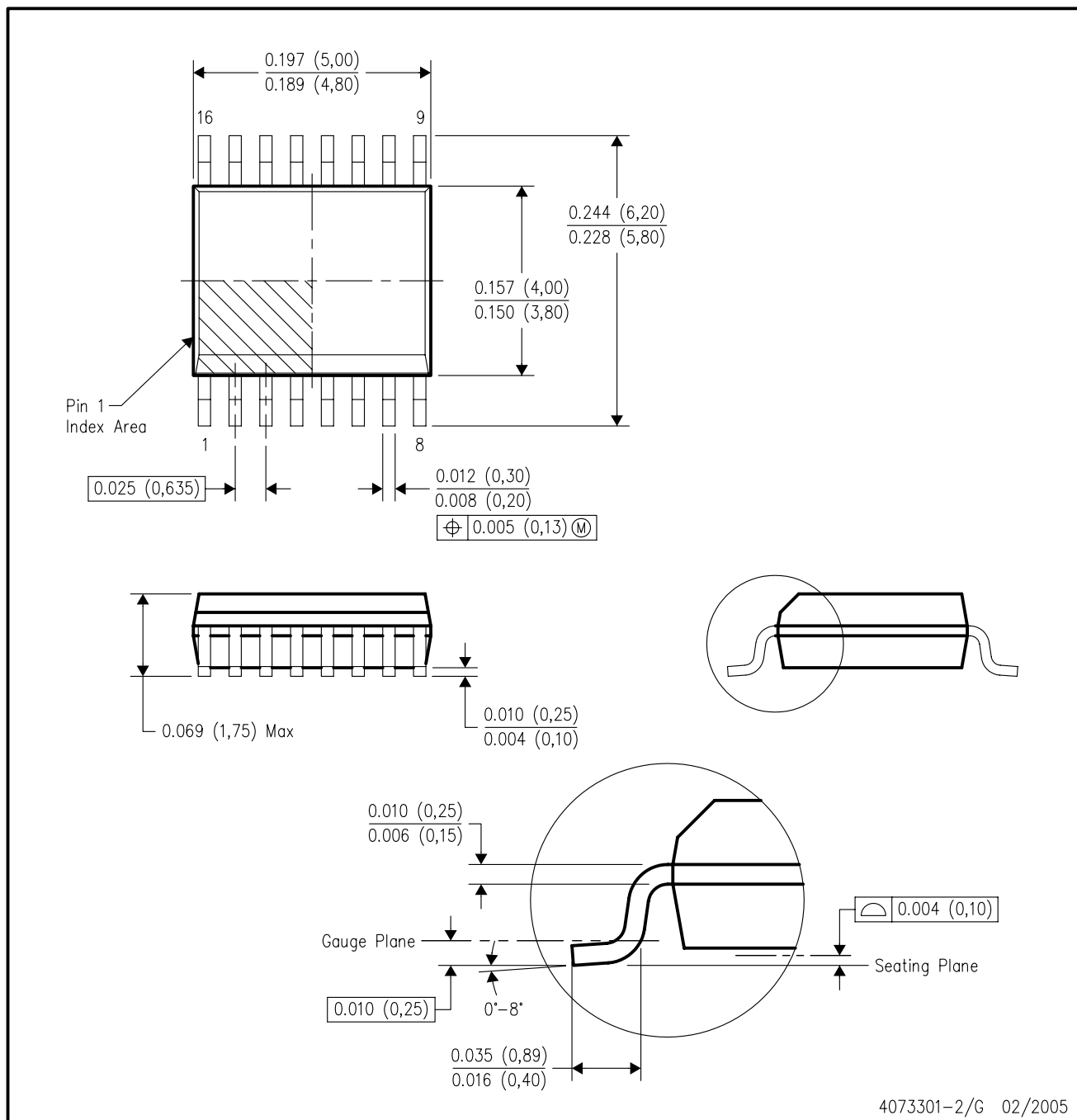


4040000-2/F 06/2004

- NOTES: A. All linear dimensions are in inches (millimeters).  
B. This drawing is subject to change without notice.  
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).  
D. Falls within JEDEC MS-013 variation AA.

## DBQ (R-PDSO-G16)

## PLASTIC SMALL-OUTLINE PACKAGE



4073301-2/G 02/2005

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